

Memorandum of Understanding
Between
VLSI Society of India (VSI)
And
Punjab Engineering College (PEC)



This Memorandum of Understanding ("MoU") entered into, on this **10th Day of April, 2024**, By and between

"VLSI Society of India (VSI)", a society promoting VLSI and Semiconductor education and research in India, Represented by Dr. Satya Gupta, President VSI

AND

"Punjab Engineering College (PEC)", Deemed to be University, Chandigarh Represented by Prof. Baldev Setia, Director, PEC

Scope and Purpose:

This MoU is being entered between VSI and PEC to define a partnership that will work together towards developing Talent, Research, Start-ups and employment opportunities in the areas of VLSI Design and Semiconductors. Both the participating organizations will work together in collaboration to achieve the following objectives:

1. VSI has more than 5000+ semiconductor professionals and volunteers around the world representing full semiconductor supply chain. Working in collaboration with PEC, the partnership will help in holistic growth of semiconductor ecosystem for Punjab region to build the required talent pipeline for the current and future growing needs that the India Semiconductor Industry is witnessing.
2. VSI and PEC will work together in developing and enhancing the VLSI Design and Semiconductors curriculum at undergraduate, post graduate and doctorate level and make these programs relevant for current and future needs of the industry. VSI will also provide help in implementing these courses.
3. VSI will provide help in setting up the required lab infrastructure for conducting the courses and projects in an effective manner.
4. VSI shall support through their industry volunteer network in providing expert lectures, projects, internship opportunities and mentoring the PEC students who are taking these courses at undergraduate, post-graduate or doctorate level.
5. VSI and PEC will collaborate in promoting and helping Research activities in VLSI Design & Semiconductors domains for current and future technology needs and trends.
6. VSI and PEC will work together for faculty development, faculty training and enhancing knowledge of the faculty members in VLSI Design and Semiconductor Areas.

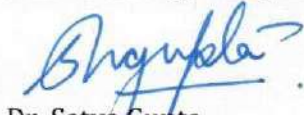
7. VSI and PEC will jointly hold workshops and training programs for students and faculty members from PEC and other institutions in the Punjab/Haryana Region.
8. VSI and PEC will work together to promote awareness regarding Electronics and Semiconductors and the career opportunities among the high school students and parents so that the students give preference to these areas while choosing their engineering branches.
9. PEC will provide help with VSI Punjab & Haryana Regional chapter in promoting VLSI Design and Semiconductors in the region, help organizing and participating in VSI organized conferences, workshops, and events.

This MoU shall be effective from the date of its execution i.e. 10th April 2024 and shall remain in force for a period of 5 years. The parties may extend the term in writing. The MoU may be terminated by either party by giving a written notice of 30 days to the other party, without assigning any reason thereof.

Parties have agreed to execute this MOU to deliver specific objectives on best efforts basis only with no financial transactions involved. Financial obligations arise/involved, if any, will be addressed through separate agreement/Contract.

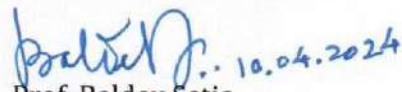
In witness whereof, the parties hereto have offered their signature from the date mentioned above.

Authorized Signatory for VSI



Dr. Satya Gupta
President, VLSI Society of India

Authorized Signatory of PEC



Prof. Baldev Setia
Director, Punjab Engineering College